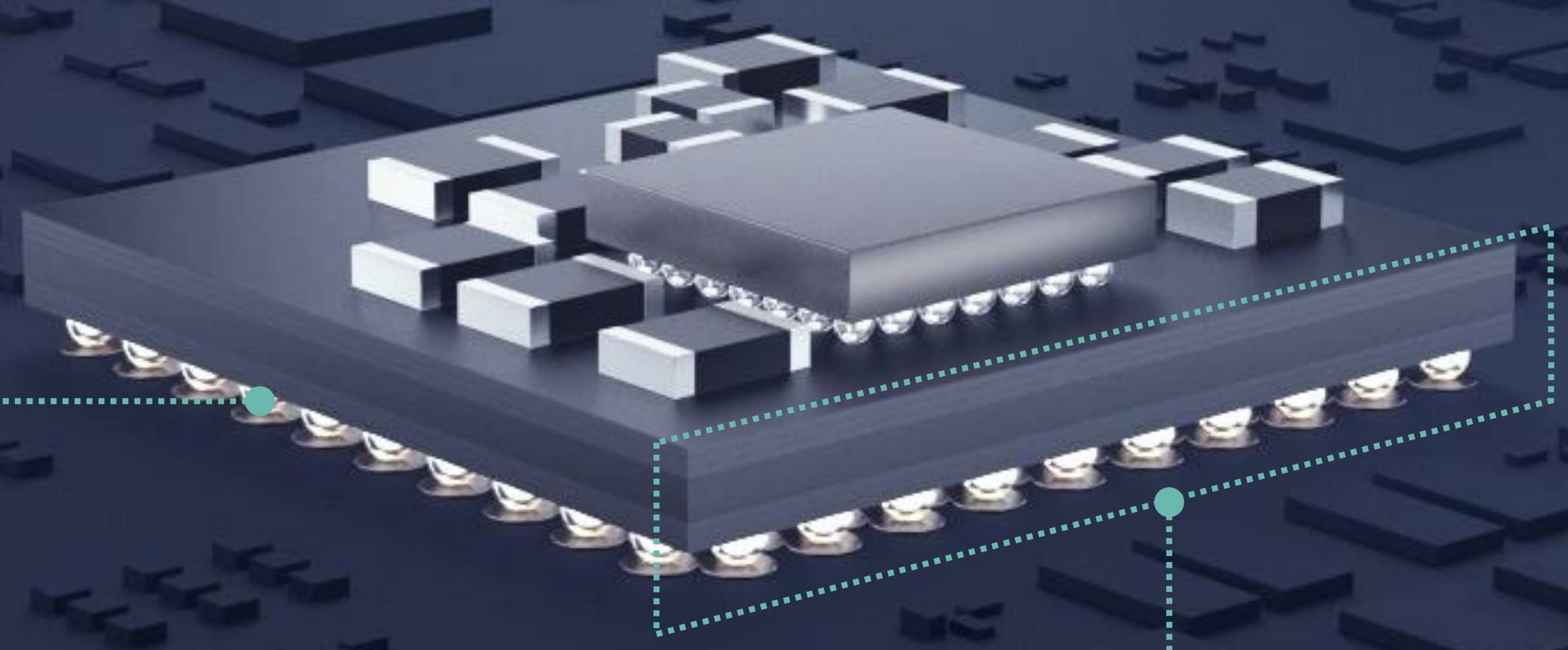
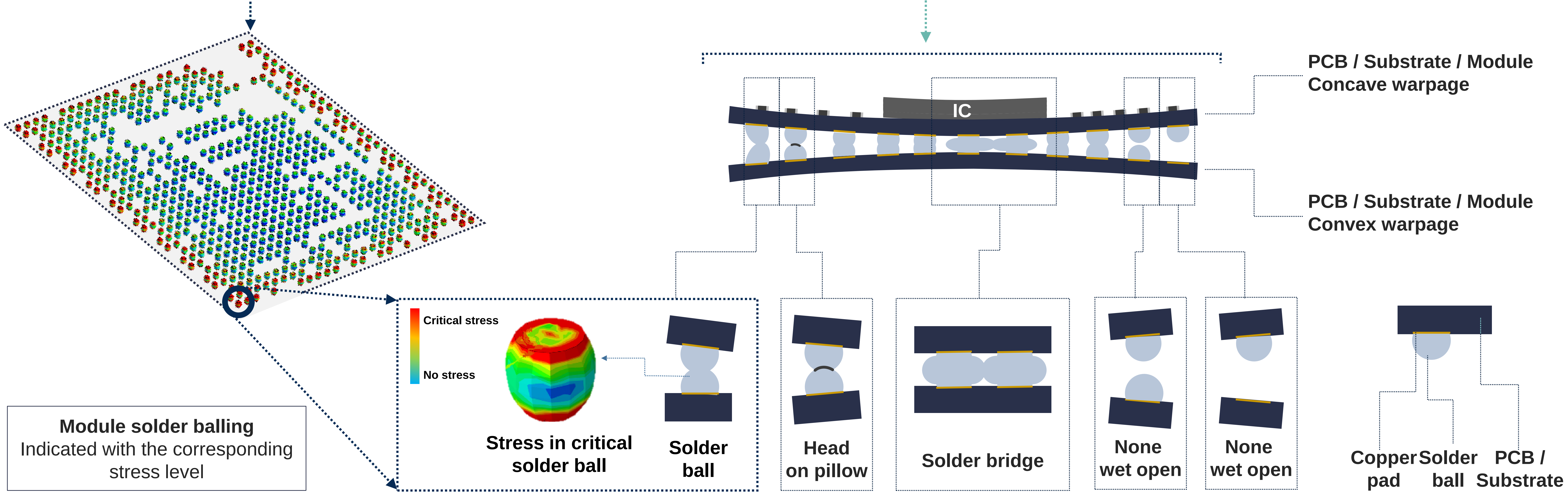
3D WARPAGE & RELIABILITY SIMULATION SERVICE

Do it right the first time



Thank you for visiting the AT&S booth. Visit ats.net for more information.



Module solder balling
Indicated with the corresponding stress level

ISSUE

Assembly, asymmetric layer construction, incorrect core, prepreg, copper distribution or materials can result in warpage or reliability issues.

3D MATERIAL CHARACTERIZATION

AT&S has industry-leading 3D material characterization and modeling capabilities.

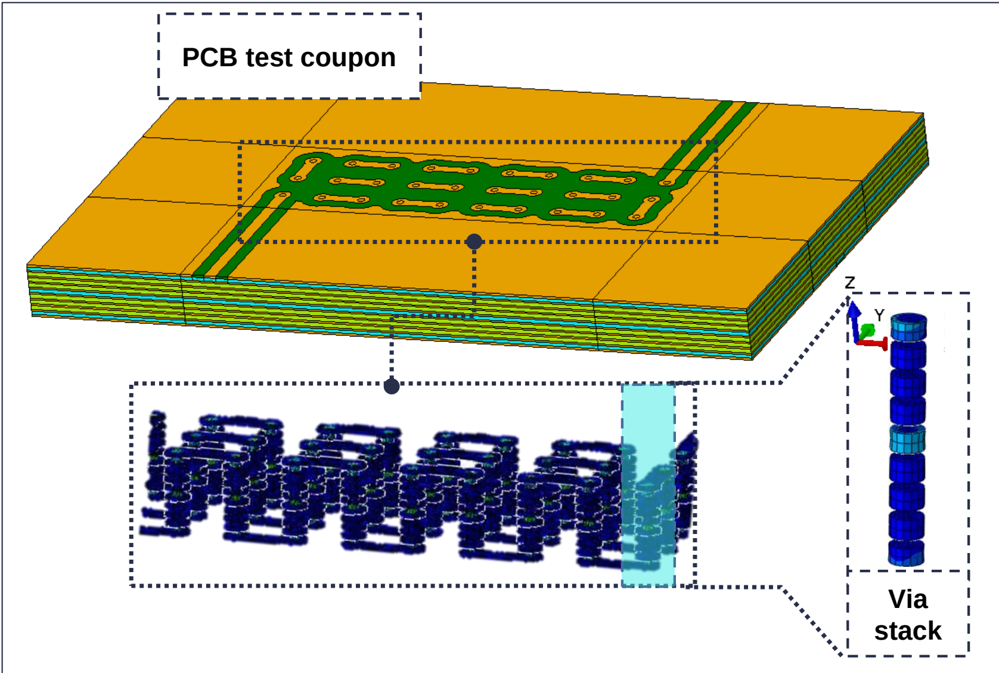
3D WARPAGE & RELIABILITY SIMULATION

With the support of AT&S warpage & reliability simulation services, issues with assembly yield or reliability can be identified in advance and statistical failure rates and life time predictions can be accurately determined

RELIABILITY SIMULATION

COPPER

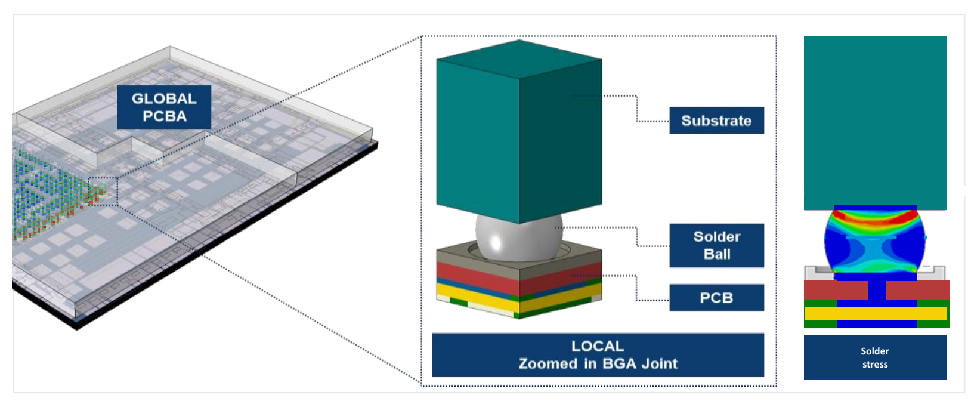
Prediction of the stress & statistical failure rates of copper structures such as vias or traces.



Reliability and stress prediction of a via stack.

SOLDER

Prediction of the stress & statistical failure rates of solder joints.

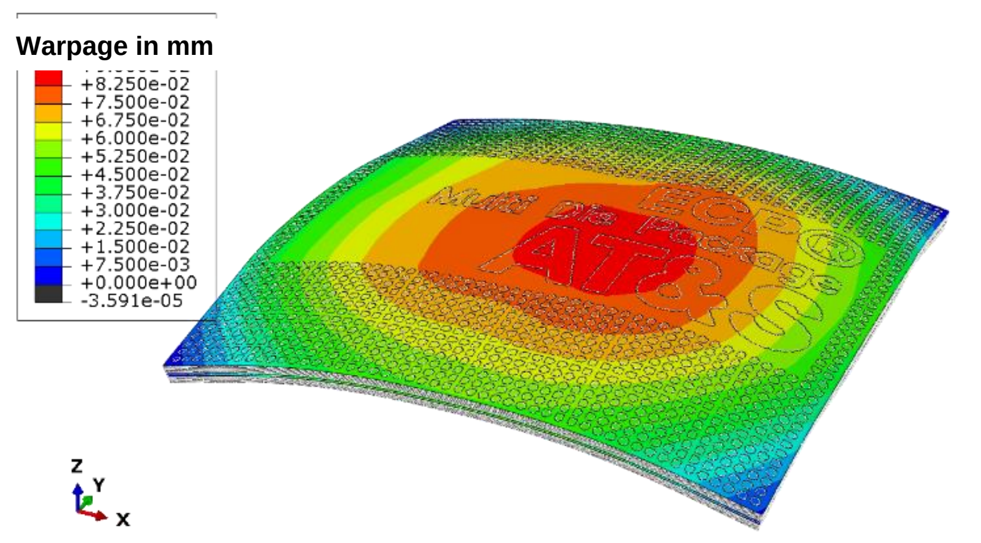


Reliability and stress prediction of solder joint connections on a module

WARPAGE SIMULATION

CARD (PCB)

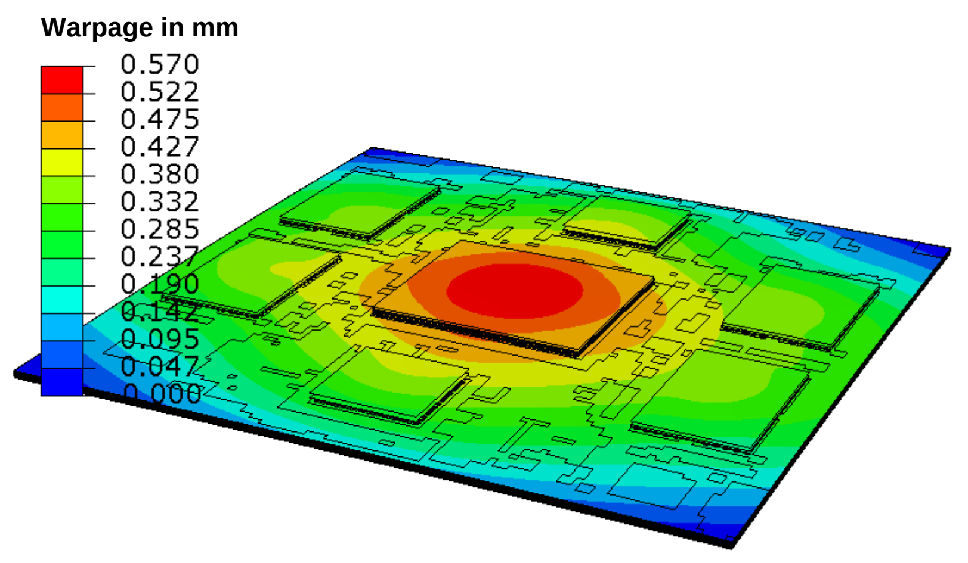
Prediction of the bare PCB warpage and identifying the key drivers.



Warpage simulation of a PCB with embedded components

ASSEMBLED SYSTEM (PCBA)

Prediction of the fully assembled PCB warpage and identifying the key drivers.



Warpage simulation of a fully assembled PCB